What is claimed is:

1. A polishing apparatus comprising:

a polishing table configured to support a polishing pad;

a plurality of film thickness sensors embedded in the polishing table, the film thickness sensors outputting a plurality of signals corresponding to a film thickness of a substrate; and

a controller configured to measure film thickness information of the substrate based on the signals acquired from the film thickness sensors,

wherein when an inner region in contact with a peripheral edge portion of the substrate is defined as an inner edge portion and an outer region in contact with the peripheral edge portion of the substrate is defined as an outer edge portion on the polishing pad, the film thickness sensors are arranged from the inner edge portion to the outer edge portion, and

wherein the controller analyzes film thickness distribution information of the substrate while identifying a notch position of the substrate based on the measured film thickness information, and outputs visualization information of a film thickness distribution with the notch position as a reference position, and

wherein, each time the polishing table makes one rotation, among the signals detected by the plurality of film thickness sensors at a specific time, a specific film thickness sensor is configured to detect a signal corresponding to the notch position of the substrate, the signal being different from signals detected by other film thickness sensors.

2. The polishing apparatus according to claim 1, wherein each of the film thickness sensors comprises a PSD sensor.

3. The polishing apparatus according to claim 1 or 2, wherein the controller comprises a median filter unit configured to perform a median filter on the signals acquired

from each of the film thickness sensors, and

wherein the median filter unit performs the median filter on the signals acquired from each of the film thickness sensors, and removes noise from the signals.

4. The polishing apparatus according to any one of claims 1 to 3, wherein the polishing apparatus comprises a wear amount detection device configured to output a signal corresponding to the amount of wear of the polishing pad, and

wherein the controller is configured to:

measure the amount of wear of the polishing pad based on the signal acquired from the wear amount detection device; and

correct film thickness information based on the measured the amount of wear of the polishing pad.

5. The polishing apparatus according to any one of claims 1 to 4, wherein the polishing apparatus comprises a display device connected to the controller, and

wherein the controller is configured to output visualization information of the film thickness distribution to the display device.

6. A method for outputting visualization information of a film thickness distribution on a substrate, comprising:

when an inner region in contact with a peripheral edge portion of the substrate is defined as an inner edge portion and an outer region in contact with the peripheral edge portion of the substrate is defined as an outer edge portion on the polishing pad, acquiring a plurality of signals corresponding to a film thickness of the substrate from a plurality of film thickness sensors arranged from the inner edge portion to the outer edge portion;

measuring film thickness information of the substrate based on the acquired signals; and

analyzing film thickness distribution information of the substrate while identifying

a notch position of the substrate based on the measured film thickness information to output visualization information of the film thickness distribution with the notch position as a reference position, and

wherein, each time the polishing table makes one rotation, among the signals detected by the plurality of film thickness sensors at a specific time, a specific film thickness sensor is configured to detect a signal corresponding to the notch position of the substrate, the signal being different from signals detected by other film thickness sensors.

7. The method according to claim 6, comprising acquiring the signals corresponding to the film thickness of the substrate from a plurality of PSD sensors.

8. The method according to claim 6 or 7, comprising performing a median filter on the acquired signals to remove noise from the signals.

9. The method according to any one of claims 6 to 8, comprising:

acquiring a signal corresponding to the amount of wear of the polishing pad from a wear amount detection device;

measuring the amount of wear of the polishing pad based on the acquired signal; and

correcting film thickness distribution information of the substrate based on the measured amount of wear of the polishing pad.

10. The method according to any one of claims 6 to 9, comprising outputting visualization information of the film thickness distribution to a display device.